

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/618,113

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For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 8697

Group Art Unit: 2891

Examiner: Zarnecke, David A.

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Sir:

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.114

Applicant hereby files the accompanying Request for Continued Examination and, therefore, requests reconsideration of this application in light of the following remarks.

Remarks begin on page 2 of this paper.